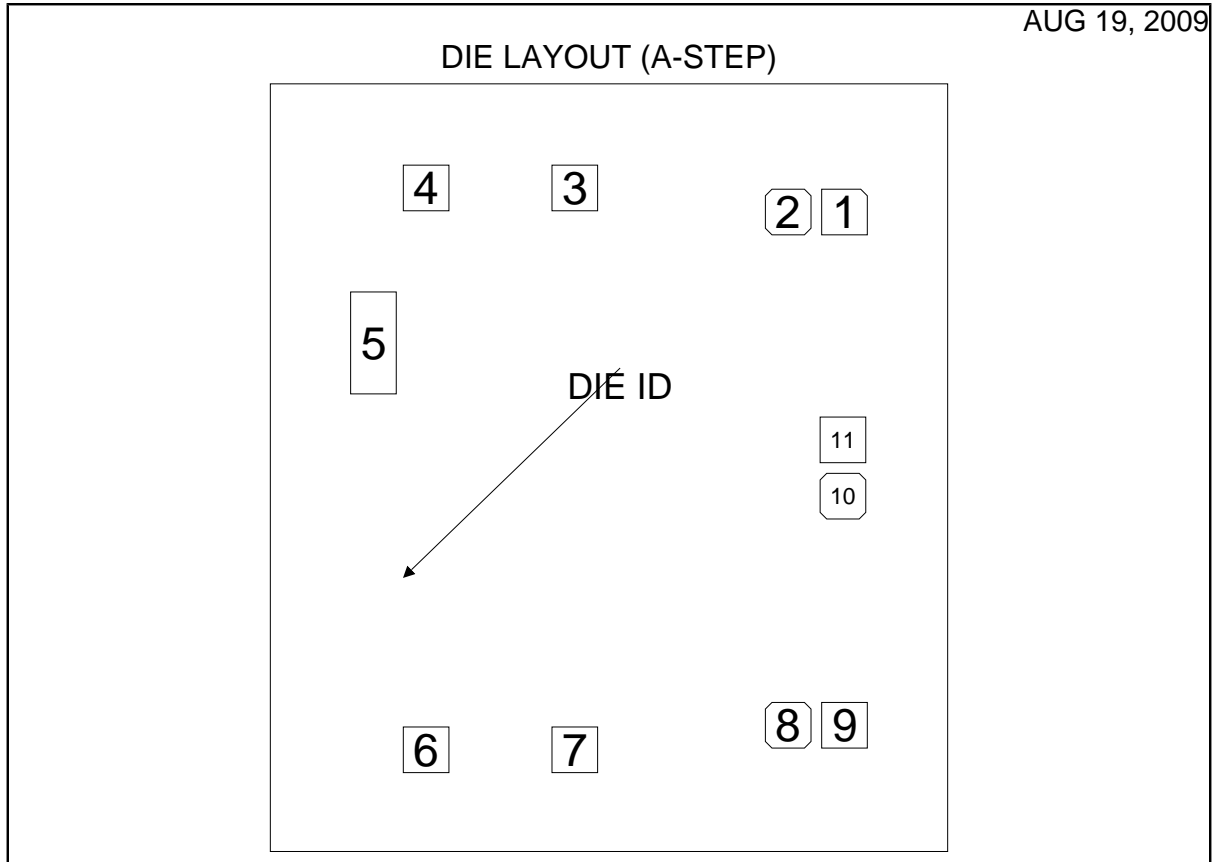


LMH6612 MDP
Single Supply 345 MHz Rail-to-Rail Output Amplifier



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6612A	Bond Pad Opening Size (min)	77.00µm x 77.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1143.00µm x 1295.40µm 45.0mils x 51.0mils	Back Side Connection	Floating or GND
Thickness	406.4µm Nominal		
Min Pitch	250.90µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
OUT A	1	397	431	77	x	77
NC	2	302	431	77	x	77
-IN A	3	-58	472	77	x	77
+IN A	4	-309	472	77	x	77
V-	5	-398	211	77	x	172
+IN B	6	-309	-476	77	x	77
-IN B	7	-58	-476	77	x	77
NC	8	302	-435	77	x	77
OUT B	9	397	-435	77	x	77
NC	10	395	-48	77	x	77
V+	11	395	47	77	x	77

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Notes

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